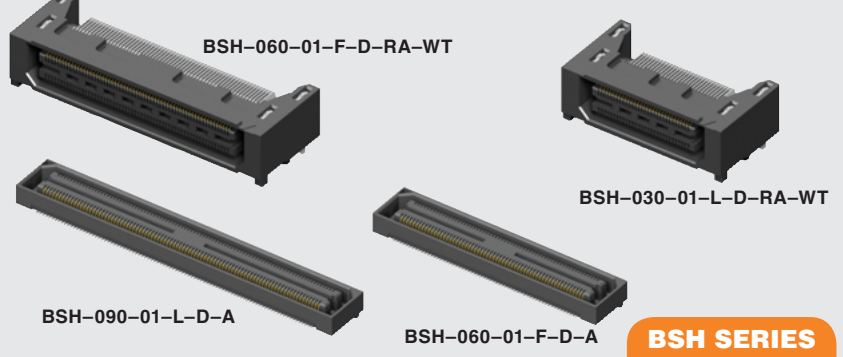




(0,50 mm) .0197"



**BSH SERIES**

# BASIC BLADE & BEAM SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?BSH](http://www.samtec.com?BSH)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50µ" (1,27 µm) Ni  
**Current Rating:** 2 A per pin (1 pin powered per row)  
**Flammability Rating:** UL 94 VO  
**Operating Temp Range:** -55°C to +125°C  
**Voltage Rating:** 275 VAC  
**Max Cycles:** 100  
**RoHS Compliant:** Yes

**Processing:**  
**Lead-Free Solderable:** Yes  
**SMT Lead Coplanarity:** (0,10 mm) .004" max (030-090) (0,15 mm) .006" max (120-150)  
**Board Stacking:**  
 For applications requiring more than two connectors per board or 90 positions or higher, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## MATED HEIGHT

| LEAD STYLE | MATED HEIGHT* |
|------------|---------------|
| -01        | (5,00) .197   |

\*Processing conditions will affect mated height.

## ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
  - Edge Mount Capability
  - 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)
- Contact Samtec.

**Note:** Some lengths, styles and options are non-standard, non-returnable.

**BSH** — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

**Mates with:**  
BTH

**-030, -050, -060, -090, -120, -150**

**-F**  
= Gold Flash on contact, Matte Tin on tail

**-L**  
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

**-C\***  
= Electro-Polished Selective  
50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

**-TR**  
= Tape & Reel (120 positions maximum)

**\*Note:** -C Plating passes 10 year MFG testing

**AGILENT LOGIC ANALYZER TEST POINT CONNECTOR**  
Specify: ASP-65067-01

**BSH** — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **RA** — **WT** — **OTHER OPTION**

**Mates with:**  
BTH

**-030, -060, -090**

**-F**  
= Gold Flash on contact, Matte Tin on tail

**-L**  
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

**-GP**  
= Guide Post